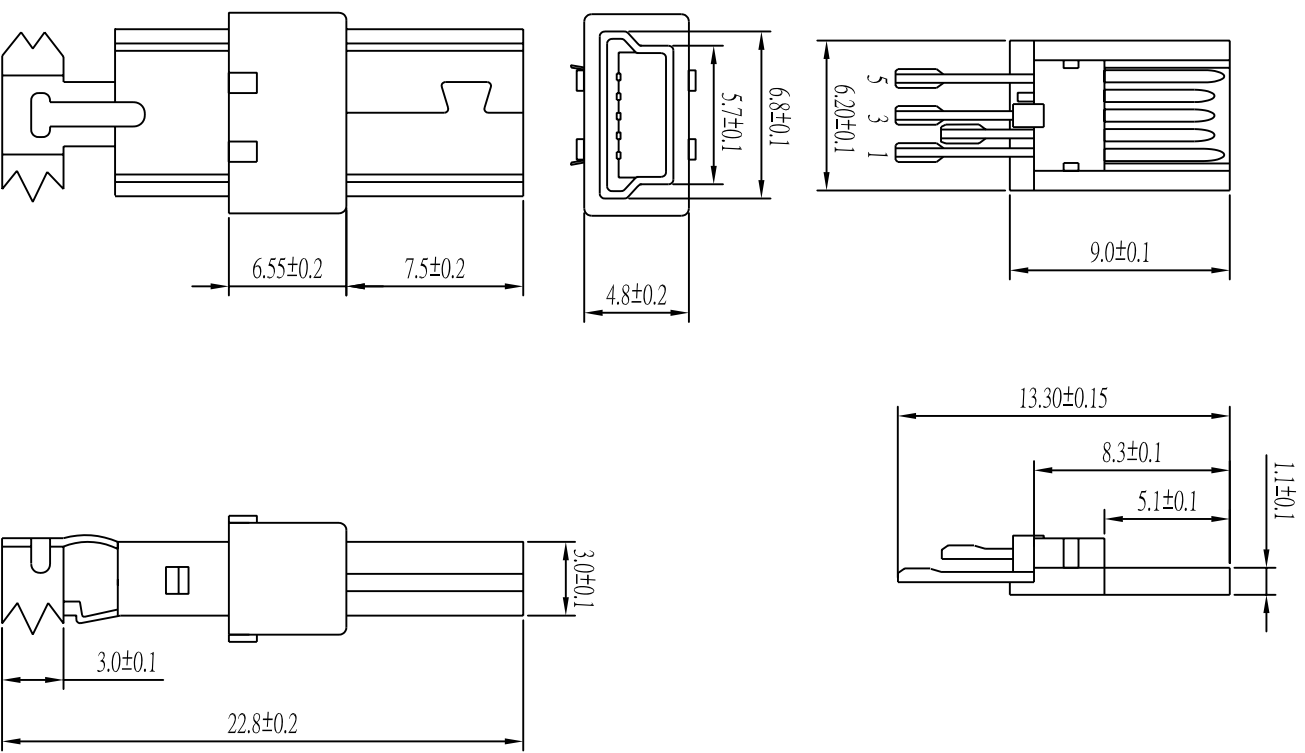


REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Note:
1.Material:
1.1 Insulator: High temperature thermoplastic with g.f.,UL94V-0
1.2 Contact: Copper alloy,t=0.25mm
1.3 Shell: Spcc,t=0.30mm

2.Specification:
2.1 Current rating: 1 A Max.
2.2 Dielectric withstanding voltage: 750 V(ac) for 1 min.
2.3 Contact resistance: 30 mΩ Max.
2.4 Insulation resistance: 1000 MΩ Min.
2.5 Total mating force: 3.0 Kgf Max.
2.6 Total unmating force: 0.5 Kgf Min.
2.7 Temperature range: -55°C~85°C



No.	Name	Qty	Part No.	Finish
8	Back-shell			
7	Front-shell			
6	Clip			No finish
5	Contact			
4	Contact			
3	Contact			Selective Au plated on mating area
2	Contact			
1	Housing			Black

PART NO:		MATERIAL:	
MODEL NO:		FINISH:	
UNIT: mm	SIZE:	COLOR:	
TOLERANCE UNSPECIFIED			
x	±0.3	DR:	
.xx	±0.20	CHK:	
.xxx	±0.100	APP:	1
ANG.	±1°	SCALE:	3:1
PART NAME: MINIUSB-SPND SOLDER		DWG NO: HC-009	REV: A0
		SHEET: 1 of 1	